

Description: 2.4GHz Ceramic Chip Antenna

PART NUMBER: W3008G

Series: Ceramic Chip Antenna



Features:

- Frequency 2400-2483.5MHz
- Size 3.2 x 1.6 x 1.1mm
- Efficiency >80%
- Gain >1.5dBi
- SMD compatible
- MSL 1

Applications:

- · 2.4GHz ISM band radios
- · Bluetooth, BLE
- WiFi 2.4GHz
- IoT, M2M devices

All dimensions are in mm / inches

Issue: 1946

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Pulse Worldwide Headquarters 15255 Innovation Drive #100 San Diego, CA 92128 USA Tel:1-858-674-8100 Pulse/Larsen Antennas 18110 SE 34th St Bldg 2 Suite 250 Vancouver, WA 98683 USA Europe Headquarters Pulse GmbH & Do, KG Zeppelinstrasse 15 Herrenberg, Germany

Pulse (Suzhou) Wireless Products Co, Inc. 99 Huo Ju Road(#29 Bldg,4th Phase Suzhou New District Jiangsu Province, Suzhou 215009 PR China Tel: 86 512 6807 9998 1



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ELECTRICAL SPECIFICATIONS

Antenna Type	Ceramic Chip
Frequency	2400-2483.5MHz
Nominal Impedance	50 Ω
VSWR	<1.6:1
Radiation Pattern	Omni
Gain	>1.5dBi
Efficiency	>80%
Polarization	Linear
Power Withstanding	2W

MECHANICAL SPECIFICATIONS

Weight	0.03 g
Overall Length	3.2 [0.126] MM [INCHES]
Over all width	1.6 [0.063] MM [INCHES]
Over all thickness	1.1 [0.043] MM [INCHES]
MSL (Moisture Sensitivity Level)	1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature	-40 / +85 ° C
Storage Temperature	-40 / +85 ° C
RoHS Compliant	Yes

2



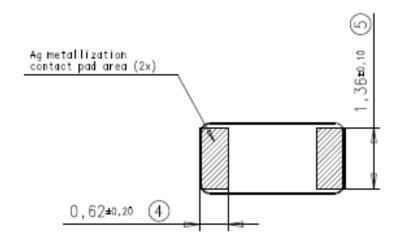


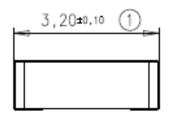
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MECHANICAL DRAWING





Antenna features		
No.	Terminal Name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm
Antenna is symmetrical. Either of terminals 1 or 2 can be Feed / GND		

Note: This type of antenna is called loaded PIFA. One pad (on the bottom of the ceramic chip antenna) that feedline and GND are connected is a basic PIFA antenna structure. And, another pad on the other side that only GND is connected is for capacitive loading. Loaded capacitive value is optimized by the gap distance between two pads on the top surface. In PIFA, there is short mechanism usually in proximity to feed. This RF shorting affects impedance and current distribution mechanism of antenna. The actual antenna top face can seem to be mirrored, however it can be used same as the non-mirrored version. Please follow the design recommendation specified in this data sheet for either case.





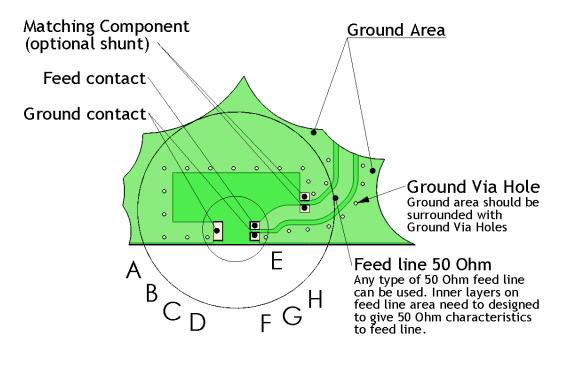
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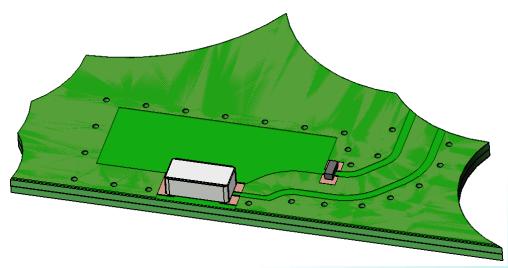
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OTHER SPECIFICATIONS

PWB Layout

Typical performance (test board size 80x37 mm, PWB ground clearance area 11.00 x 6.25 mm) Antenna placed 80mm edge center position.













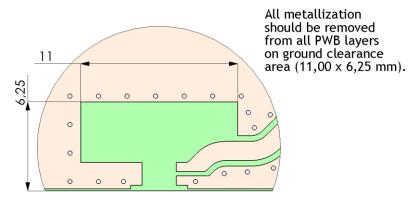
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OTHER SPECIFICATIONS

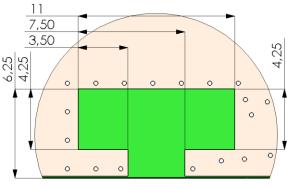
Ground cleared under antenna, clearance area 11.00 x 6.25 mm

Ground clearance area (11,00 x 6,25 mm)



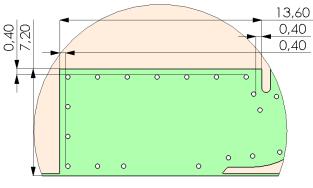
DETAIL A

Opening in bottom/inner ground layers



DETAIL B

Opening in other layers (no ground/ RF)



DETAIL C





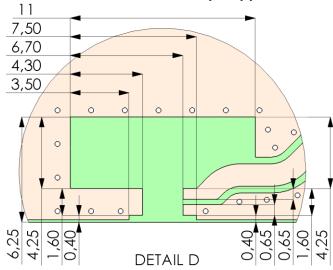
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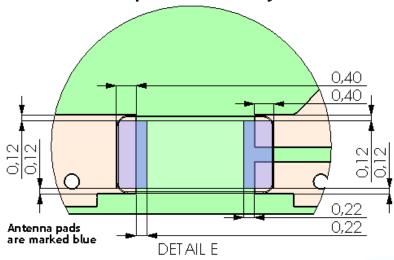
OTHER SPECIFICATIONS

PWB pad dimensions and antenna position

Pad dimensions in top copper



Antenna position on PWB layout





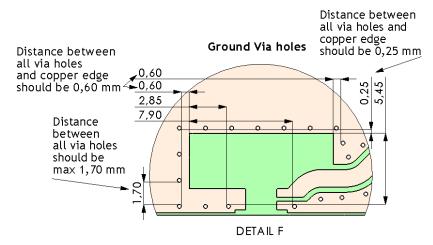


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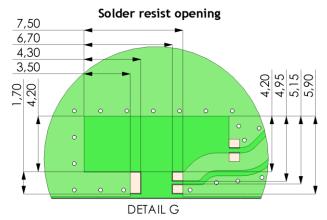
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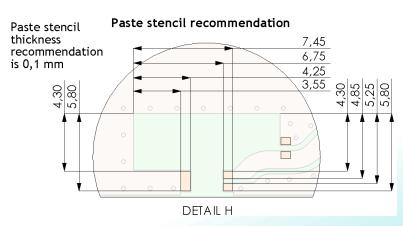
OTHER SPECIFICATIONS

Typical Ground via hole placement in PWB layout



Solder resist opening and paste stencil recommendations







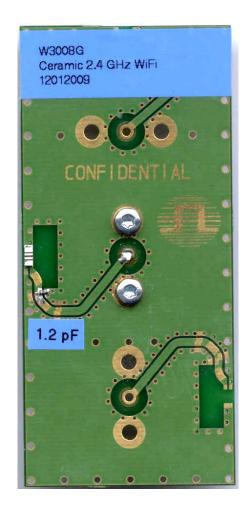
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TEST SETUP

All RF parameters measured on 37x80mm evaluation board. Antenna placement on side center position of PCB long edge. Shunt 1.2pF capacitor for matching.





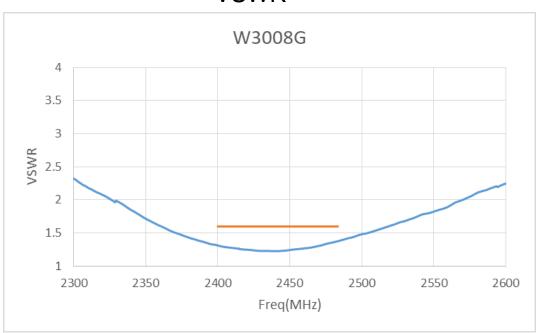
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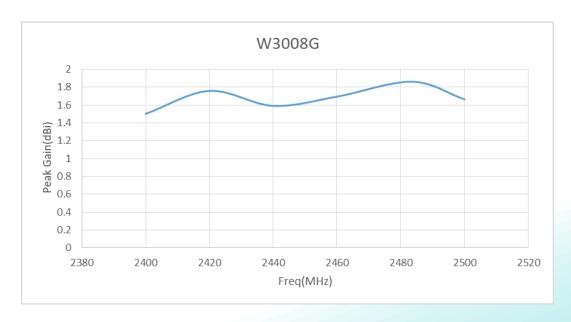
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CHARTS

VSWR



Peak Gain





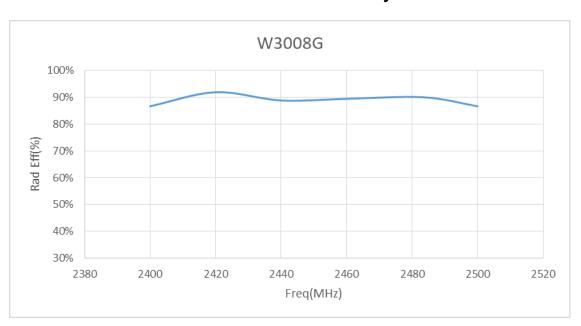
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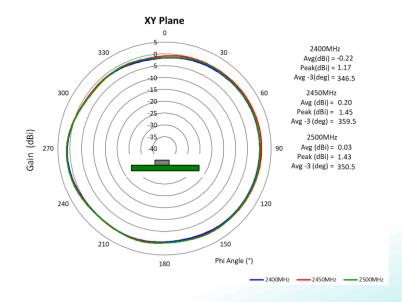
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CHARTS

Radiation Efficiency



Radiation pattern X-Y plane







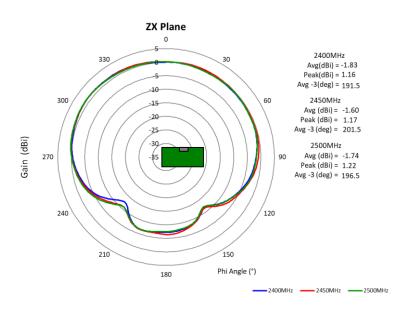
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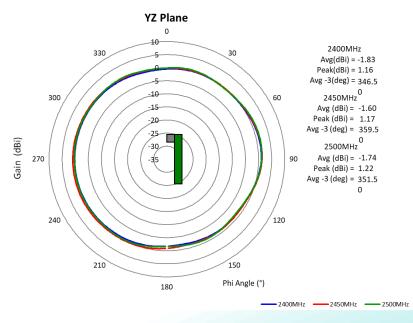
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CHARTS

Radiation pattern Z-X plane



Radiation pattern Y-Z plane



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ROHS





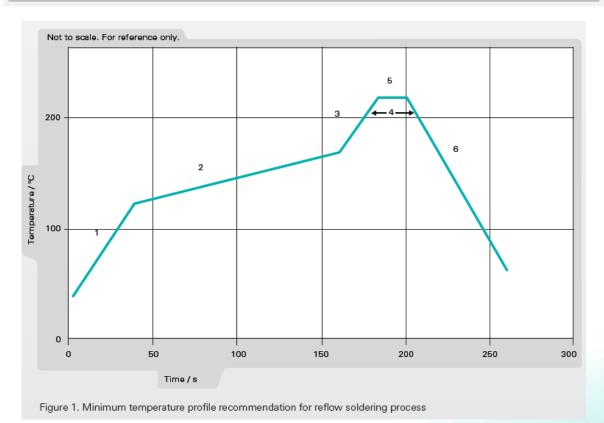
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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 ℃ for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s



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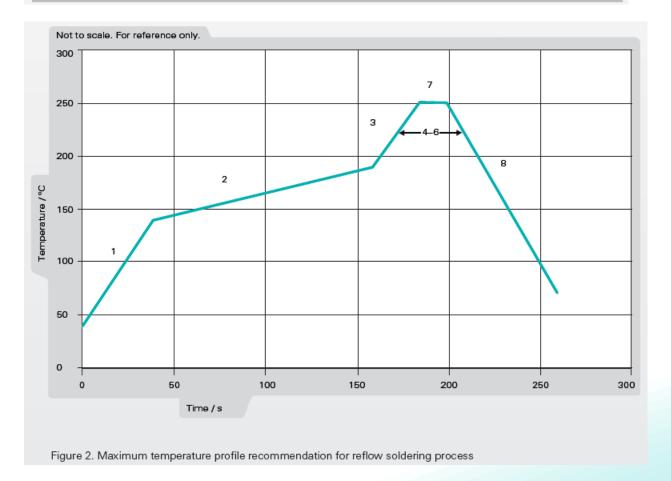


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	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s





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PACKAGING-1

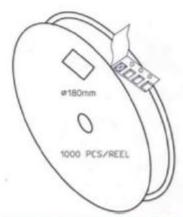
3000pcs antennas per 7" reel

5pcs 7" reel per inner package box

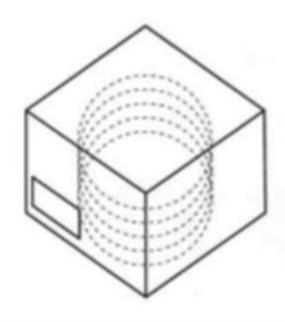
2pcs inner box per out box

Total 30000pcs antenna per out box

Out box size: 390mmx215mmx165mm







LEVEL

NOT MOISTURE SENSITIVE

1

These Devices do not require special storage conditions provided:

- They are maintained at conditions equal to or less than 30°C and 85% RH.
- They are solder reflowed at a peak body temperture which does not exceed 260°C.

Note: Level and body temperture defined by IPC/JEDEC J-STD-020

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ROHS

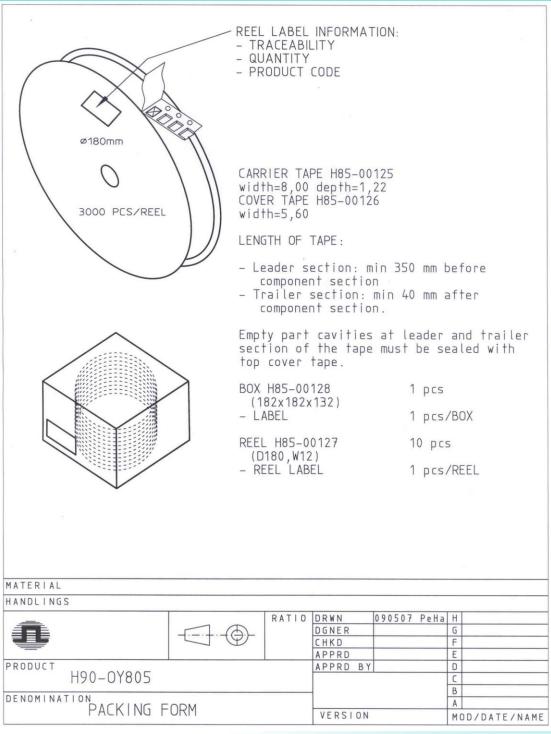


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PACKAGING-2



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15

单击下面可查看定价,库存,交付和生命周期等信息

>>Pulse(普思)